AMENDMENTS TO THE CLAIMS

Please substitute the following claims for the pending claims with the same numbers respectively:

Claims 1-2 (Cancelled):

Claim 3 (Currently amended): A method for making a conductive electroless plating powder comprising the steps of:

(I) allowing [[the]] core particles which have a noble metal ion-capturing ability to capture noble metal ions, and reducing the noble metal ions so that the surfaces of the core particles support the noble metal;

(II) dispersing the core particles in an initial thin film-forming solution containing nickel ions, a reducing agent, and a complexing agent comprising an amine to prepare an aqueous suspension, and reducing the nickel ions to form initial thin nickel films on a surface of each of the core particles; and

(III) adding a nickel ion-containing solution containing the [[same]] complexing agent and a reducing agent-containing solution individually and simultaneously to the aqueous suspension containing the core particles provided with the

initial thin nickel films and the complexing agent to perform electroless plating;

adjusting the amounts of the nickel ion-containing solution added and the reducing agent-containing solution added;

adjusting the initial concentration of the complexing agent in the aqueous suspension; and

adjusting the concentration of the complexing agent in the nickel ion-containing solution, so as to maintain the concentration of the complexing agent in the aqueous suspension in the range of 0.003 to 10 moles/l in said step of (III) adding a nickel ion-containing solution containing the same complexing agent and a reducing agent-containing solution.

Claim 4 (Cancelled):

Claim 5 (Currently amended): [[A]] The method according to claim 3, further comprising the step of using glycine or ethylenediamine as the complexing agent.

Claim 6 (Currently amended): [[A]] The method according to claim [[4]] 3, further comprising the step of using glycine or ethylenediamine as the complexing agent.

Claim 7 (Currently amended): [[A]] The method according to claim 3, further comprising the step of providing, before said step (III), a ratio of the sum of the surface areas of the core particles contained in the aqueous suspension to the volume of the aqueous suspension between 0.1 to 15 m^2/l.

Claim 8 (Cancelled):

Claim 9 (Currently amended): [[A]] The method according to claim 5, further comprising the step of providing, before said step (III), a ratio of the sum of the surface areas of the core particles contained in the aqueous suspension to the volume of the aqueous suspension between 0.1 to 15 m^2/l.

Claim 10 (Currently amended): [[A]] The method according to claim 3, further comprising the step of imparting the noble metal ion-capturing ability to the core particles by a surface treatment.

Please add the following new claims 11-33 as follows:

Claim 11 (New): The method according to claim 10, wherein said step of imparting the noble metal ion-capturing ability to

the core particles by a surface treatment includes adjusting the amount of the surface treatment in the range between 0.3 and 100 mg/m^2 of the surface area of the core particles.

Claim 12 (New): The method according to claim 3, wherein said step of (II) dispersing the core particles in an initial thin film-forming solution containing nickel ions, a reducing agent, and a complexing agent includes using glycine or ethylenediamine for the complexing agent; and

wherein said step of (III) adding a nickel ion-containing solution containing the complexing agent and a reducing agent-containing solution includes using glycine or ethylenediamine for the complexing agent.

Claim 13 (New): The method according to claim 3, wherein said step of adjusting the initial concentration of the complexing agent includes using glycine or ethylenediamine.

Claim 14 (New): The method according to claim 3, further comprising the step of providing, before said step of (III) adding a nickel ion-containing solution containing the complexing agent and a reducing agent-containing solution, a ratio of the sum of the surface areas of the core particles contained in the

aqueous suspension to the volume of the aqueous suspension between 0.1 to 15 m^2/l.

Claim 15 (New): The method according to claim 12, further comprising the step of providing, before said step of (III) adding a nickel ion-containing solution containing the complexing agent and a reducing agent-containing solution, a ratio of the sum of the surface areas of the core particles contained in the aqueous suspension to the volume of the aqueous suspension between 0.1 to 15 m^2/l.

Claim 16 (New): A method for making a conductive electroless plating powder including columnar structures extending in a direction of a thickness of a nickel film comprising the steps of:

allowing the core particles which have a noble metal ion-capturing ability to capture noble metal ions, and reducing the noble metal ions so that the surfaces of the core particles support the noble metal;

dispersing the core particles in an initial thin film-forming solution containing nickel ions, a reducing agent, and a complexing agent comprising an amine to prepare an aqueous

suspension, and reducing the nickel ions to form initial thin nickel films on a surface of each of the core particles;

providing a ratio of the sum of the surface areas of the core particles contained in the aqueous suspension to the volume of the aqueous suspension between 0.1 to 15 m^2/l;

adding a nickel ion-containing solution containing the same complexing agent and a reducing agent-containing solution individually and simultaneously to the aqueous suspension containing the core particles provided with the initial thin nickel films and the complexing agent to perform electroless plating;

adjusting the amounts of the nickel ion-containing solution added and the reducing agent-containing solution added;

adjusting the initial concentration of the complexing agent in the aqueous suspension;

adjusting the concentration of the complexing agent in the nickel ion-containing solution, so as to maintain the concentration of the complexing agent in the aqueous suspension in the range of 0.003 to 10 moles/l in said step of adding a nickel ion-containing solution containing the same complexing agent and a reducing agent-containing solution.

Claim 17 (New): The method according to claim 16, wherein said step of allowing core particles includes dispersing the core particles in a weekly acidic aqueous solution of a noble metal salt which is palladium chloride so that the noble metal ions are captured by the surfaces of the core particles.

Claim 18 (New): The method according to claim 16, wherein said step of dispersing the core particles in an initial thin film-forming solution containing nickel ions includes forming an initial thin film in the range of the thickness between 0.001 and 2 μm.

Claim 19 (New): The method according to claim 18, wherein said step of dispersing the core particles in an initial thin film-forming solution containing nickel ions includes forming an initial thin film in the range of the thickness between 0.005 and 1 μm.

Claim 20 (New): The method according to claim 16, wherein said step of dispersing the core particles in an initial thin film-forming solution containing nickel ions includes adjusting the concentration of the nickel ions in the initial thin film-forming solution in the range between 2.0×10^{-4} and 1.0 mol/l.

Claim 21 (New): The method according to claim 20, wherein said step of dispersing the core particles in an initial thin film-forming solution containing nickel ions includes adjusting the concentration of the nickel ions in the initial thin film-forming solution in the range between 1.0×10^{-3} and 0.1 mol/l.

Claim 22 (New): The method according to claim 16, wherein said step of dispersing the core particles in an initial thin film-forming solution containing nickel ions includes adjusting the reducing agent in the initial thin film-forming solution in the range between 4×10^{-4} and 2.0 mol/l.

Claim 23 (New): The method according to claim 22, wherein said step of dispersing the core particles in an initial thin film-forming solution containing nickel ions includes adjusting the reducing agent in the initial thin film-forming solution in the range between 2.0×10^{-3} and 0.2 mol/l.

Claim 24 (New): The method according to claim 16, wherein said step of dispersing the core particles in an initial thin film-forming solution containing nickel ions, a reducing agent,

and a complexing agent includes using sodium borohydride or dimethylamine borane for the reducing agent.

Claim 25 (New): The method according to claim 16, wherein said step of dispersing the core particles in an initial thin film-forming solution containing a complexing agent includes using glycine for the complexing agent; and

wherein said step of adding a nickel ion-containing solution containing the complexing agent includes using glycine for the complexing agent.

Claim 26 (New): The method according to claim 16, wherein said step of adjusting the initial concentration of the complexing agent includes using glycine.

Claim 27 (New): The method according to claim 16, wherein said step of adding a nickel ion-containing solution containing the complexing agent and a reducing agent-containing solution includes adjusting the concentration of the nickel ions in the nickel ion-containing solution in the range between 0.1 and 1.2 mol/l.

Claim 28 (New): The method according to claim 27, wherein said step of adding a nickel ion-containing solution containing the complexing agent and a reducing agent-containing solution includes adjusting the concentration of the nickel ions in the nickel ion-containing solution in the range between 0.5 and 1.0 mol/l.

Claim 29 (New): The method according to claim 16, wherein said step of adding a nickel ion-containing solution containing the complexing agent and a reducing agent-containing solution includes adjusting the concentration of the reducing agent in the nickel ion-containing solution in the range between 0.1 and 20 mol/l.

Claim 30 (New): The method according to claim 29, wherein said step of adding a nickel ion-containing solution containing the complexing agent and a reducing agent-containing solution includes adjusting the concentration of the reducing agent in the nickel ion-containing solution in the range between 1 and 10 mol/l.

Claim 31 (New): The method according to claim 16, wherein said step of adding a nickel ion-containing solution containing

the complexing agent and a reducing agent-containing solution includes adjusting the deposition rate of nickel between 1 and 10,000 nanometers/hour.

Claim 32 (New): The method according to claim 31, wherein said step of adding a nickel ion-containing solution containing the complexing agent and a reducing agent-containing solution includes adjusting the deposition rate of nickel between 5 and 300 nanometers/hour.

Claim 33 (New): A method for making a conductive electroless plating powder comprising the steps of:

(I) allowing the core particles which have a noble metal ion-capturing ability to capture noble metal ions, and reducing the noble metal ions so that the surfaces of the core particles support the noble metal;

(II) dispersing the core particles in an initial thin film-forming solution containing nickel ions, a reducing agent, and a complexing agent comprising an amine to prepare an aqueous suspension, and reducing the nickel ions to form initial thin nickel films on a surface of each of the core particles;

(III) adding a nickel ion-containing solution containing the same complexing agent and a reducing agent-containing solution

individually and simultaneously to the aqueous suspension containing the core particles provided with the initial thin nickel films and the complexing agent to perform electroless plating; and

(IV) forming a gold plating layer as a top layer on the nickel film.

Claim 34 (New): A method for making a conductive electroless plating powder including columnar structures extending in a direction of a thickness of a nickel film comprising the steps of:

allowing the core particles which have a noble metal ion-capturing ability to capture noble metal ions, and reducing the noble metal ions so that the surfaces of the core particles support the noble metal;

dispersing the core particles in an initial thin film-forming solution containing nickel ions, a reducing agent, and a complexing agent comprising an amine to prepare an aqueous suspension, and reducing the nickel ions to form initial thin nickel films on a surface of each of the core particles;

providing a ratio of the sum of the surface areas of the core particles contained in the aqueous suspension to the volume of the aqueous suspension between 0.1 to 15 m^2/l;

adding a nickel ion-containing solution containing the same complexing agent and a reducing agent-containing solution individually and simultaneously to the aqueous suspension containing the core particles provided with the initial thin nickel films and the complexing agent to perform electroless plating;

adjusting the amounts of the nickel ion-containing solution added and the reducing agent-containing solution added;

adjusting the initial concentration of the complexing agent in the aqueous suspension;

adjusting the concentration of the complexing agent in the nickel ion-containing solution, so as to maintain the concentration of the complexing agent in the aqueous suspension in the range of 0.003 to 10 moles/l in said step of adding a nickel ion-containing solution containing the same complexing agent and a reducing agent-containing solution; and

forming a gold plating layer as a top layer on the nickel film.